

33082M172



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Takanori Mimura, et al.
Serial No. : 10/647,433 Art Unit : 1765
Filed : August 26, 2003 Examiner : Binh X. Tran
For : SILICON ETCHING METHOD

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure under 37 C.F.R. 1.56, Applicants enclose an Information Disclosure Citation Form (PTO-1449).

It is respectfully requested that the cited documents be considered by the Examiner in the above-identified patent application and that the cited documents be made officially of record therein. It is further requested that a listing of the same appear on the face of any patent which may issue from this application.

No Official Action on the merits yet has issued for this application. In accordance with 37 C.F.R. §1.97, no fee is considered due in connection with the filing of this Statement.

Respectfully submitted,
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FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT		ATTY. DOCKET 033082.172	SERIAL NO. 10/647,433
		APPLICANT: Takanori Mimura, et al.	
		FILING DATE 8/26/03	GROUP ART UNIT 1765

U.S. PATENT DOCUMENTS

*Examiner's Initials		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB-CLASS	FILING DATE, IF APPROPRIATE
	AA	5,423,941	6/13/95	Komura et al.			
	AB	4,793,897	12/27/88	Dunfield, et al.			
	AC	6,303,512	10/16/01	Laermer et al.			
	AD						

FOREIGN PATENT DOCUMENTS

*Examiner's Initials		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION YES NO
	AE						
	AF						
	AG						
	AH						
	AI						

OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, Etc.)

	AJ		
	AK		
EXAMINER:		DATE CONSIDERED:	
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>			

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